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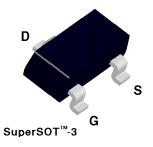
## NDS355AN N-Channel Logic Level Enhancement Mode Field Effect Transistor

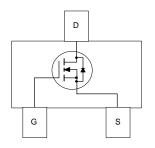
#### **General Description**

SuperSOT<sup>TM</sup>-3 N-Channel logic level enhancement mode power field effect transistors are produced using ON Semiconductor's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage applications in notebook computers, portable phones, PCMCIA cards, and other battery powered circuits where fast switching, and low inline power loss are needed in a very small outline surface mount package.

#### **Features**

- Industry standard outline SOT-23 surface mount package using proprietary SuperSOT<sup>™</sup>-3 design for superior thermal and electrical capabilities.
- High density cell design for extremely low R<sub>DS(ON)</sub>.
- Exceptional on-resistance and maximum DC current capability.
- Compact industry standard SOT-23 surface mount package.





Absolute Maximum Ratings T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter		NDS355AN	Units	
V <sub>DSS</sub>	Drain-Source Voltage		30	V	
V <sub>GSS</sub>	Gate-Source Voltage - Continuous		±20	V	
I <sub>D</sub>	Maximum Drain Current - Continuous	(Note 1a)	1.7	А	
	- Pulsed		10		
P <sub>D</sub>	Maximum Power Dissipation	(Note 1a)	0.5	W	
		(Note 1b)	0.46		
T <sub>J</sub> ,T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to 150	°C	
THERMA	L CHARACTERISTICS	<u>.</u>			
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	250	°C/W	
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	(Note 1)	75	°C/W	

Symbol	Parameter	Conditions		Min	Тур	Max	Units
OFF CHA	RACTERISTICS						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		30			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 24 \text{ V}, V_{GS} = 0 \text{ V}$				1	μΑ
			T <sub>J</sub> =125°C			10	μΑ
I <sub>GSSF</sub>	Gate - Body Leakage, Forward	$V_{GS} = 20 V_{DS} = 0 V$				100	nA
I <sub>GSSR</sub>	Gate - Body Leakage, Reverse	V <sub>GS</sub> = -20 V, V <sub>DS</sub> = 0 V				-100	nA
ON CHAR	ACTERISTICS (Note 2)	·					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		1	1.6	2	V
			T <sub>J</sub> =125°C	0.5	1.2	1.5	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 4.5 \text{ V}, I_{D} = 1.7 \text{ A}$			0.105	0.125	Ω
			T <sub>J</sub> =125°C		0.16	0.23	
		$V_{GS} = 10 \text{ V}, I_{D} = 1.9 \text{ A}$			0.065	0.085	
I <sub>D(ON)</sub>	On-State Drain Current	$V_{GS} = 4.5 \text{ V}, V_{DS} = 5 \text{ V}$		6			Α
g <sub>FS</sub>	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 1.7 \text{ A}$			3.5		S
DYNAMIC	CHARACTERISTICS	·					
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0  MHz			195		pF
C <sub>oss</sub>	Output Capacitance				135		pF
C <sub>rss</sub>	Reverse Transfer Capacitance				48		pF
SWITCHI	NG CHARACTERISTICS (Note 2)						
$t_{d(on)}$	Turn - On Delay Time	$V_{DD} = 10 \text{ V}, I_{D} = 1 \text{ A},$ $V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$			10	20	ns
t <sub>r</sub>	Turn - On Rise Time				13	25	ns
$t_{d(off)}$	Turn - Off Delay Time				13	25	ns
t <sub>f</sub>	Turn - Off Fall Time				4	10	ns
t <sub>d(on)</sub>	Turn - On Delay Time	$V_{DD} = 5 \text{ V}, I_{D} = 1 \text{ A},$			10	20	ns
t <sub>r</sub>	Turn - On Rise Time	$V_{GS} = 4.5 \text{ V}, R_{GEN} = 6 \Omega$			32	60	ns
t <sub>d(off)</sub>	Turn - Off Delay Time				10	20	ns
t <sub>f</sub>	Turn - Off Fall Time				5	10	ns
$Q_g$	Total Gate Charge	$V_{DS} = 10 \text{ V}, I_{D} = 1.7 \text{ A},$			3.5	5	nC
$Q_{gs}$	Gate-Source Charge	V <sub>GS</sub> = 5 V			0.8		nC
$Q_{gd}$	Gate-Drain Charge				1.7		nC

Electrical Characteristics (T <sub>A</sub> = 25°C unless otherwise noted)								
Symbol	Parameter	Conditions		Тур	Max	Units		
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS								
Is	Maximum Continuous Drain-Source Diode Forward Current				0.42	Α		
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current				10	Α		
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> =0.42 A (Note 2)		0.8	1.2	V		

#### Notes:

1.  $R_{g,u}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{g,u}$  is guaranteed by design while  $\mathbf{R}_{\text{\tiny \thetaCA}}$  is determined by the user's board design.

$$P_D(t) = \frac{T_I - T_A}{R_{0J}A(t)} = \frac{T_J - T_A}{R_{0J} \cdot d^2 R_{0D}(t)} = I_D^2(t) \times R_{DS \ (ON \ )} \otimes_{T_J}$$
Typical  $R_{0,N}$  using the board layouts shown below on 4.5°x5" FR-4 PCB in a still air environment:

a. 250°C/W when mounted on a 0.02 in² pad of 2oz copper.

b. 270°C/W when mounted on a 0.001 in² pad of 2oz copper.





Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  2.0%.

## **Typical Electrical Characteristics**

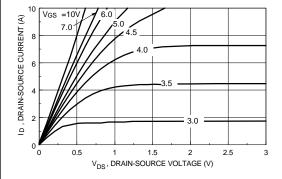


Figure 1. On-Region Characteristics.

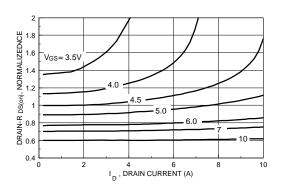


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

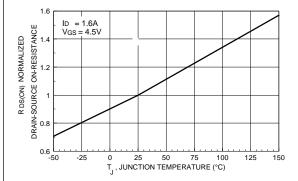


Figure 3. On-Resistance Variation with Temperature.

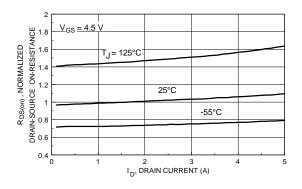


Figure 4. On-Resistance Variation with Drain Current and Temperature.

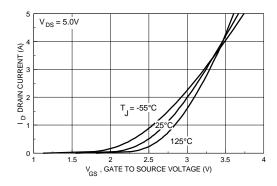


Figure 5. Transfer Characteristics.

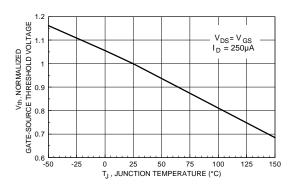


Figure 6. Gate Threshold Variation with Temperature.

## **Typical Electrical Characteristics (continued)**

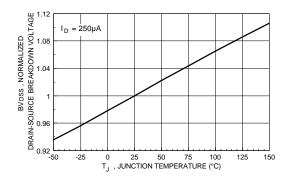


Figure 7. Breakdown Voltage Variation with Temperature.

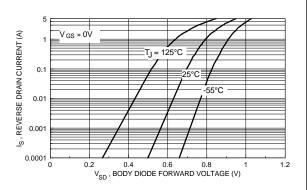


Figure 8. Body Diode Forward Voltage Variation with Source Current and Temperature.

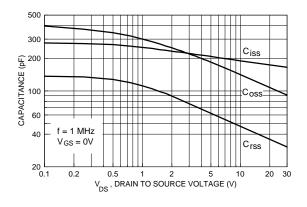


Figure 9. Capacitance Characteristics.

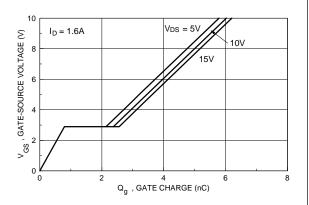


Figure 10. Gate Charge Characteristics.

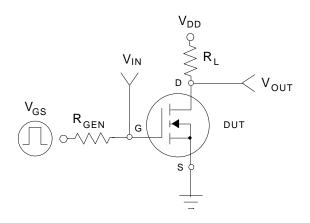


Figure 11. Switching Test Circuit.

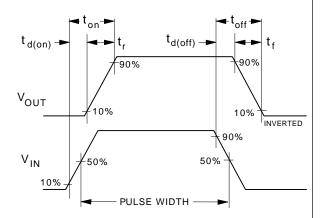
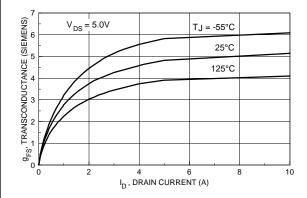


Figure 12. Switching Waveforms.

## **Typical Electrical Characteristics (continued)**



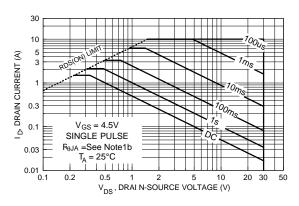
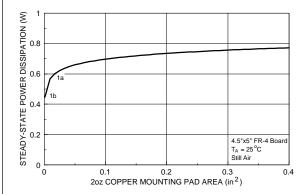
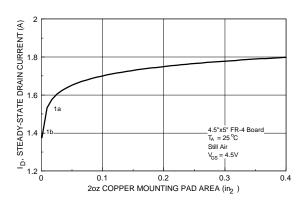


Figure 13. Transconductance Variation with Drain Current and Temperature.

Figure 14. Maximum Safe Operating Area.





Figue 15. SuperSOT<sup>™</sup>-3 Maximum
Steady-State Power Dissipation versus Copper
Mounting Pad Area.

Figure 16. Maximum Steady-State Drain Current versus Copper Mounting Pad Area.

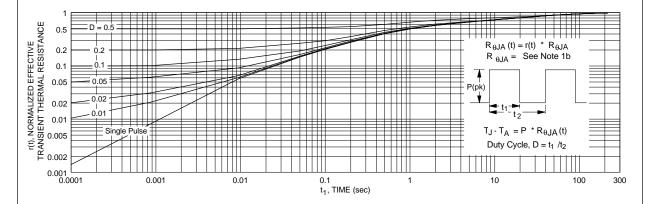


Figure 17. Transient Thermal Response Curve.

Note: Characterization performed using the conditions described in note 1b. Transient thermal response will change depending on the circuit board design.

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